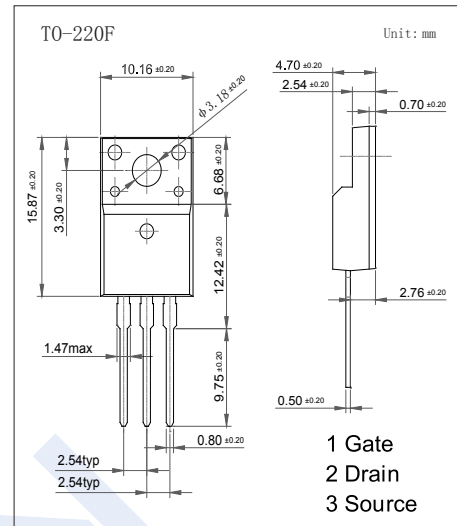
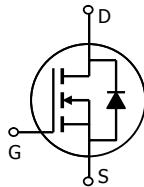


## N-Channel MOSFET

### KX6N80F

#### ■ Features

- $V_{DS} (V) = 800V$
- $I_D = 7 A$  ( $V_{GS} = 10V$ )
- $R_{DS(ON)} < 1.9 \Omega$  ( $V_{GS} = 10V$ )
- Low Gate Charge (Typ. 27 nC)
- Fast switching
- 100% Avalanche Tested



#### ■ Absolute Maximum Ratings $T_a = 25^\circ C$

| Parameter                               | Symbol     | Rating     | Unit          |
|-----------------------------------------|------------|------------|---------------|
| Drain-Source Voltage                    | $V_{DS}$   | 800        | V             |
| Gate-Source Voltage                     | $V_{GS}$   | $\pm 30$   |               |
| Continuous Drain Current                | $I_D$      | 7          | A             |
|                                         |            | 4.2        |               |
| Pulsed Drain Current (Note.1)           | $I_{DM}$   | 28         |               |
| Power Dissipation                       | $P_D$      | 56         | W             |
| - Derate above $25^\circ C$             |            | 0.44       | W/ $^\circ C$ |
| Single Pulsed Avalanche Energy (Note.2) | $E_{AS}$   | 650        | mJ            |
| Repetitive Avalanche Energy (Note.1)    | $E_{AR}$   | 16.7       |               |
| Peak Diode Recovery $dv/dt$ (Note.3)    | $dv/dt$    | 4.5        | V/ns          |
| Thermal Resistance.Junction- to-Ambient | $R_{thJA}$ | 62.5       | $^\circ C/W$  |
| Thermal Resistance.Junction- to-Case    | $R_{thJC}$ | 2.25       |               |
| Junction Temperature                    | $T_J$      | 150        | $^\circ C$    |
| Storage Temperature Range               | $T_{stg}$  | -55 to 150 |               |

Note.1: Repetitive Rating : Pulse width limited by maximum junction temperature

Note.2:  $L = 25mH$ ,  $I_{AS} = 7A$ ,  $V_{DD} = 50V$ ,  $R_G = 25 \Omega$ , Starting  $T_J = 25^\circ C$

Note.3:  $I_{SD} \leq 7A$ ,  $di/dt \leq 200A/\mu s$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ C$

## N-Channel MOSFET

### KX6N80F

#### ■ Electrical Characteristics Ta = 25℃

| Parameter                                 | Symbol              | Test Conditions                                                             | Min | Typ  | Max  | Unit |
|-------------------------------------------|---------------------|-----------------------------------------------------------------------------|-----|------|------|------|
| Drain-Source Breakdown Voltage            | V <sub>DSS</sub>    | I <sub>D</sub> =250 μA, V <sub>GS</sub> =0V                                 | 800 |      |      | V    |
| Zero Gate Voltage Drain Current           | I <sub>DSS</sub>    | V <sub>DS</sub> =800V, V <sub>GS</sub> =0V                                  |     |      | 10   | μA   |
|                                           |                     | V <sub>DS</sub> =640V, V <sub>GS</sub> =0V, T <sub>C</sub> =125℃            |     |      | 100  |      |
| Gate-Body Leakage Current                 | I <sub>GSS</sub>    | V <sub>DS</sub> =0V, V <sub>GS</sub> =±30V                                  |     |      | ±100 | nA   |
| Gate Threshold Voltage                    | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA                   | 3   |      | 5    | V    |
| Static Drain-Source On-Resistance         | R <sub>DS(on)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A                                  |     |      | 1.9  | Ω    |
| Input Capacitance                         | C <sub>iss</sub>    | V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1MHz                           |     | 1300 |      | pF   |
| Output Capacitance                        | C <sub>oss</sub>    |                                                                             |     | 120  |      |      |
| Reverse Transfer Capacitance              | C <sub>rss</sub>    |                                                                             |     | 10   |      |      |
| Total Gate Charge                         | Q <sub>g</sub>      | V <sub>GS</sub> =10V, V <sub>DS</sub> =640V, I <sub>D</sub> =7A<br>(Note.1) |     | 27   |      | nC   |
| Gate Source Charge                        | Q <sub>gs</sub>     |                                                                             |     | 8    |      |      |
| Gate Drain Charge                         | Q <sub>gd</sub>     |                                                                             |     | 11   |      |      |
| Turn-On DelayTime                         | t <sub>d(on)</sub>  | V <sub>DS</sub> =400V, I <sub>D</sub> =7A, R <sub>G</sub> =25 Ω<br>(Note.1) |     | 40   |      | ns   |
| Turn-On Rise Time                         | t <sub>r</sub>      |                                                                             |     | 100  |      |      |
| Turn-Off DelayTime                        | t <sub>d(off)</sub> |                                                                             |     | 50   |      |      |
| Turn-Off Fall Time                        | t <sub>f</sub>      |                                                                             |     | 60   |      |      |
| Body Diode Reverse Recovery Time          | t <sub>rr</sub>     | I <sub>F</sub> =7A, di/dt= 100A/ μs, V <sub>GS</sub> =0<br>(Note.1)         |     | 650  |      | μC   |
| Body Diode Reverse Recovery Charge        | Q <sub>rr</sub>     |                                                                             |     | 7    |      |      |
| Maximum Body-Diode Continuous Current     | I <sub>S</sub>      |                                                                             |     |      | 7    | A    |
| Pulsed Drain-Source Diode Forward Current | I <sub>SM</sub>     |                                                                             |     |      | 28   |      |
| Diode Forward Voltage                     | V <sub>SD</sub>     | I <sub>S</sub> =7A, V <sub>GS</sub> =0V                                     |     |      | 1.5  | V    |

Note.1: Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%

## N-Channel MOSFET

### KX6N80F

#### ■ Typical Characteristics

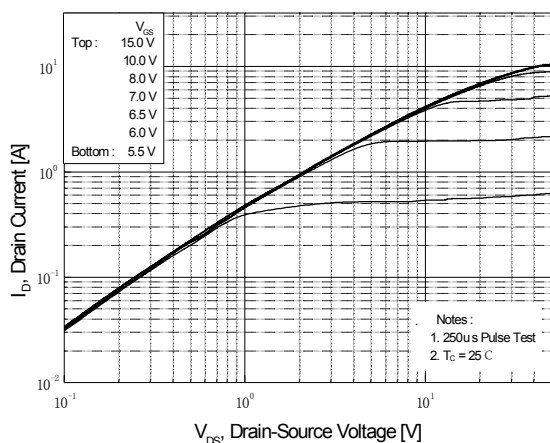


Figure 1. On-Region Characteristics

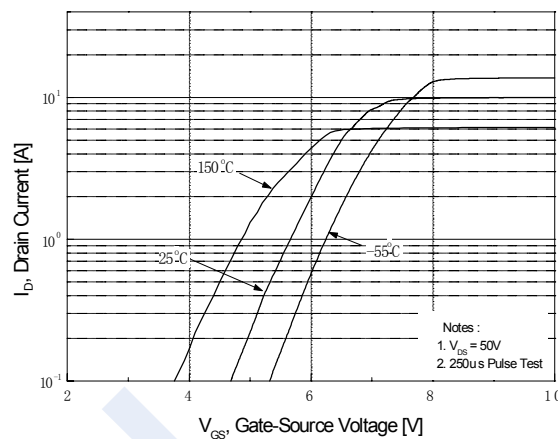


Figure 2. Transfer Characteristics

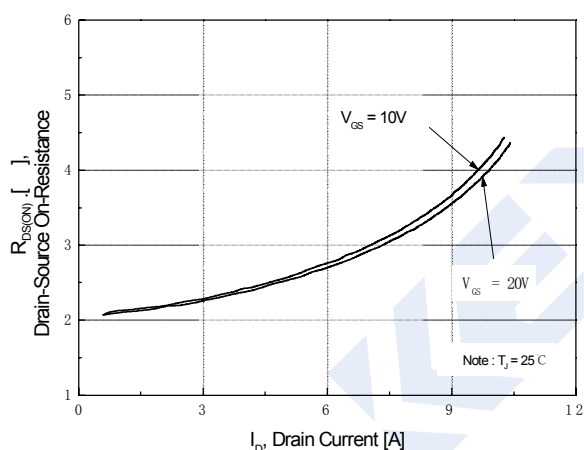


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

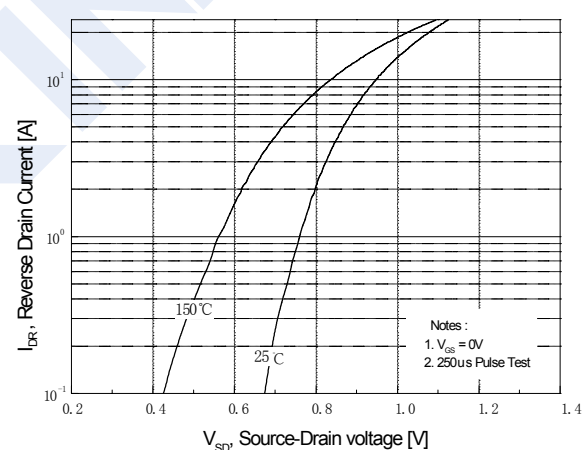


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

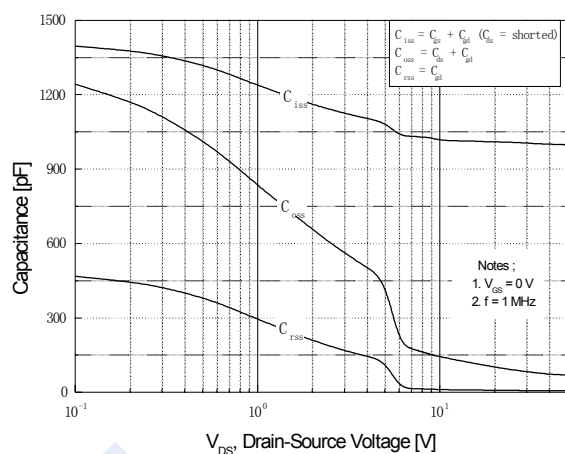


Figure 5. Capacitance Characteristics

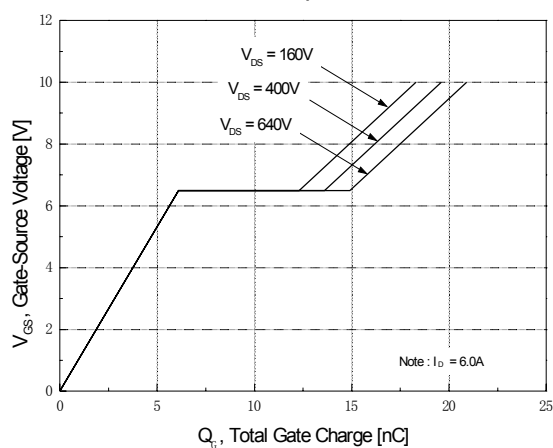


Figure 6. Gate Charge Characteristics

## N-Channel MOSFET

### KX6N80F

#### ■ Typical Characteristics

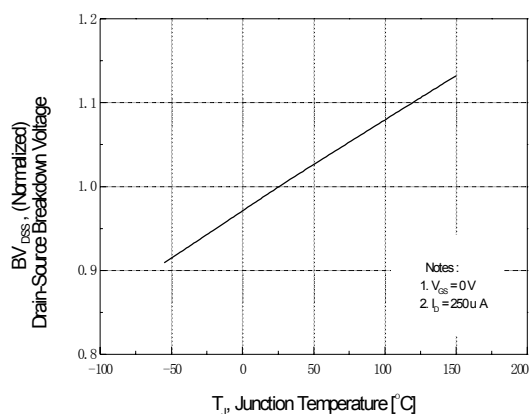


Figure 7. Breakdown Voltage Variation vs Temperature

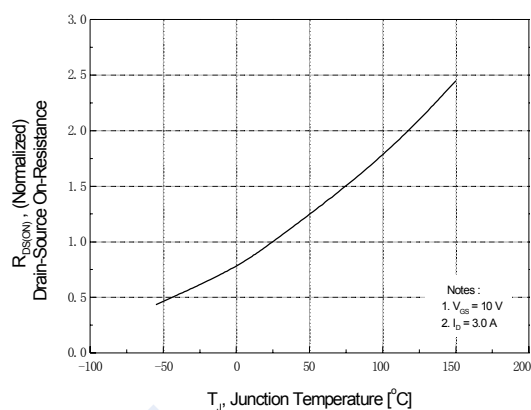


Figure 8. On-Resistance Variation vs Temperature

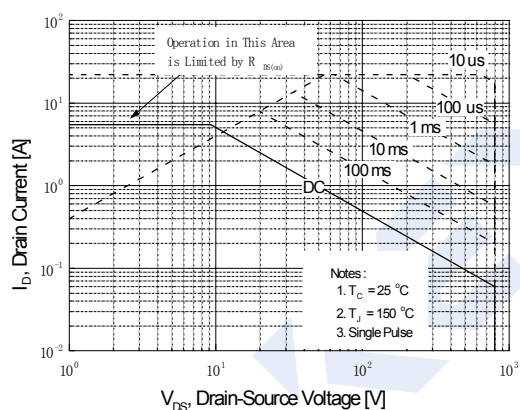


Figure 9. Maximum Safe Operating Area for KX6N80F

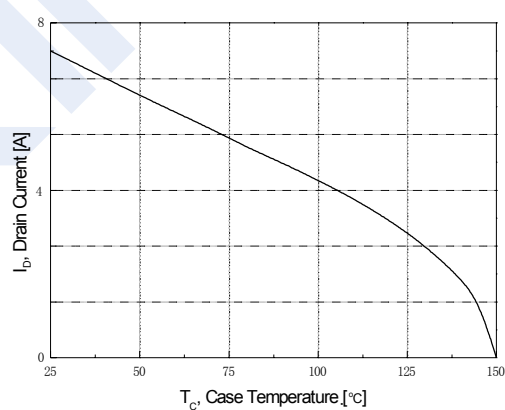


Figure 10. Maximum Drain Current vs Case Temperature

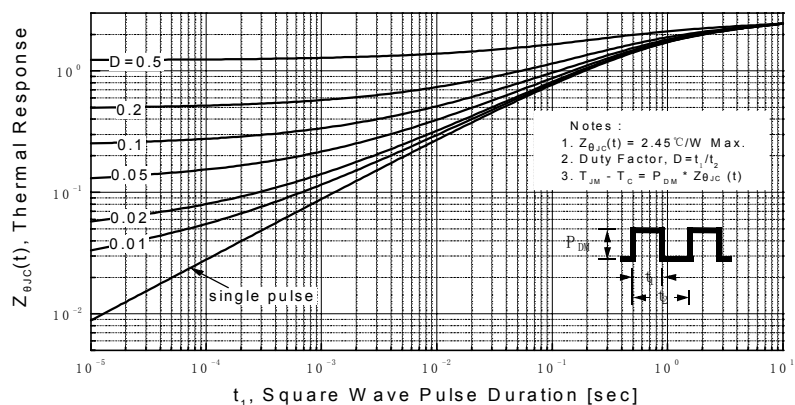
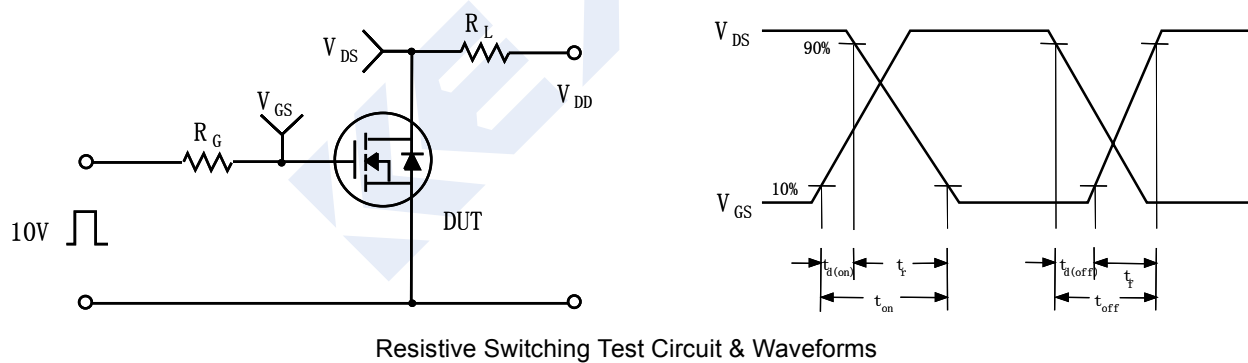
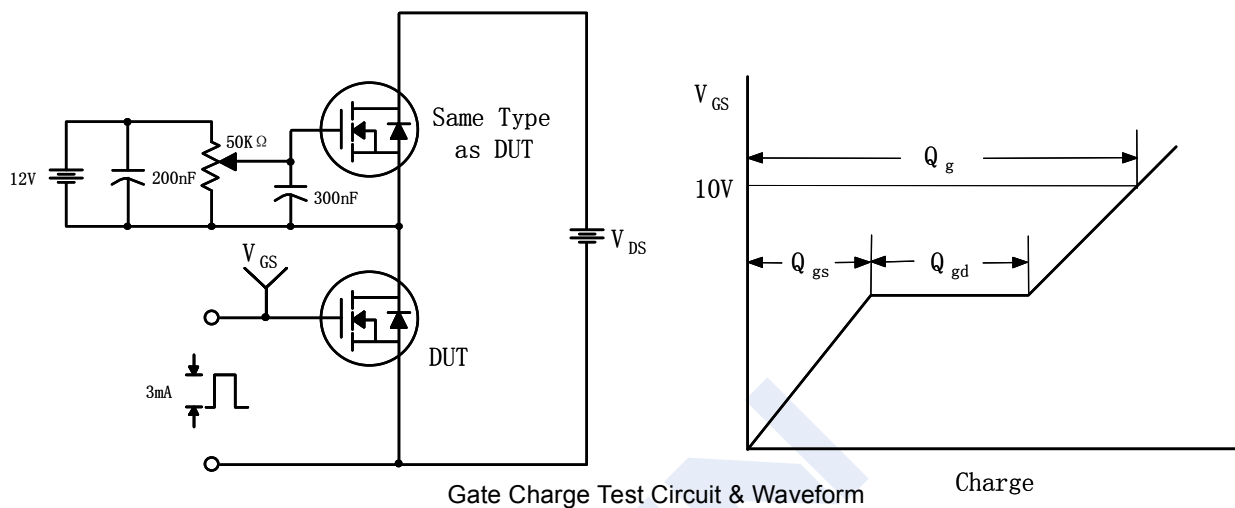


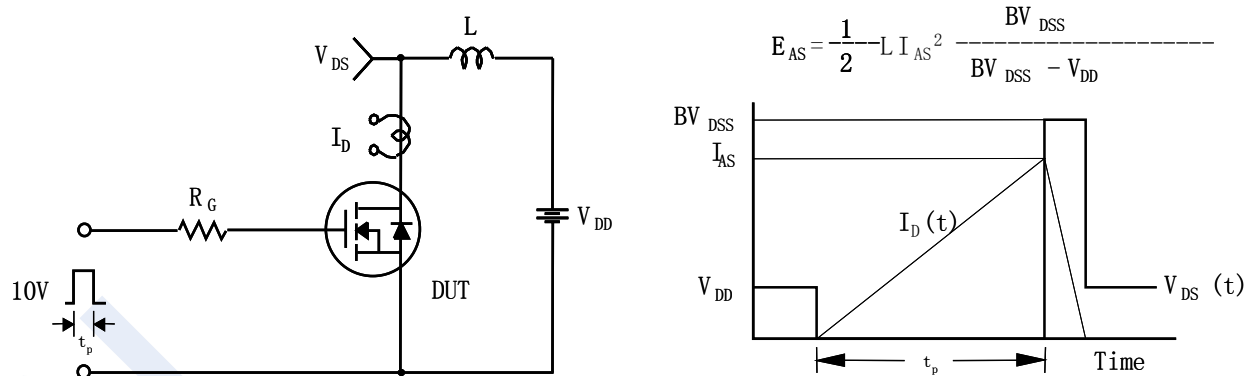
Figure 11. Transient Thermal Response Curve for KX6N80F

## N-Channel MOSFET KX6N80F

### ■ Typical Characteristics



### Unclamped Inductive Switching Test Circuit & Waveforms



## N-Channel MOSFET

### KX6N80F

#### ■ Typical Characteristics

Peak Diode Recovery dv/dt Test Circuit &amp; Waveforms

